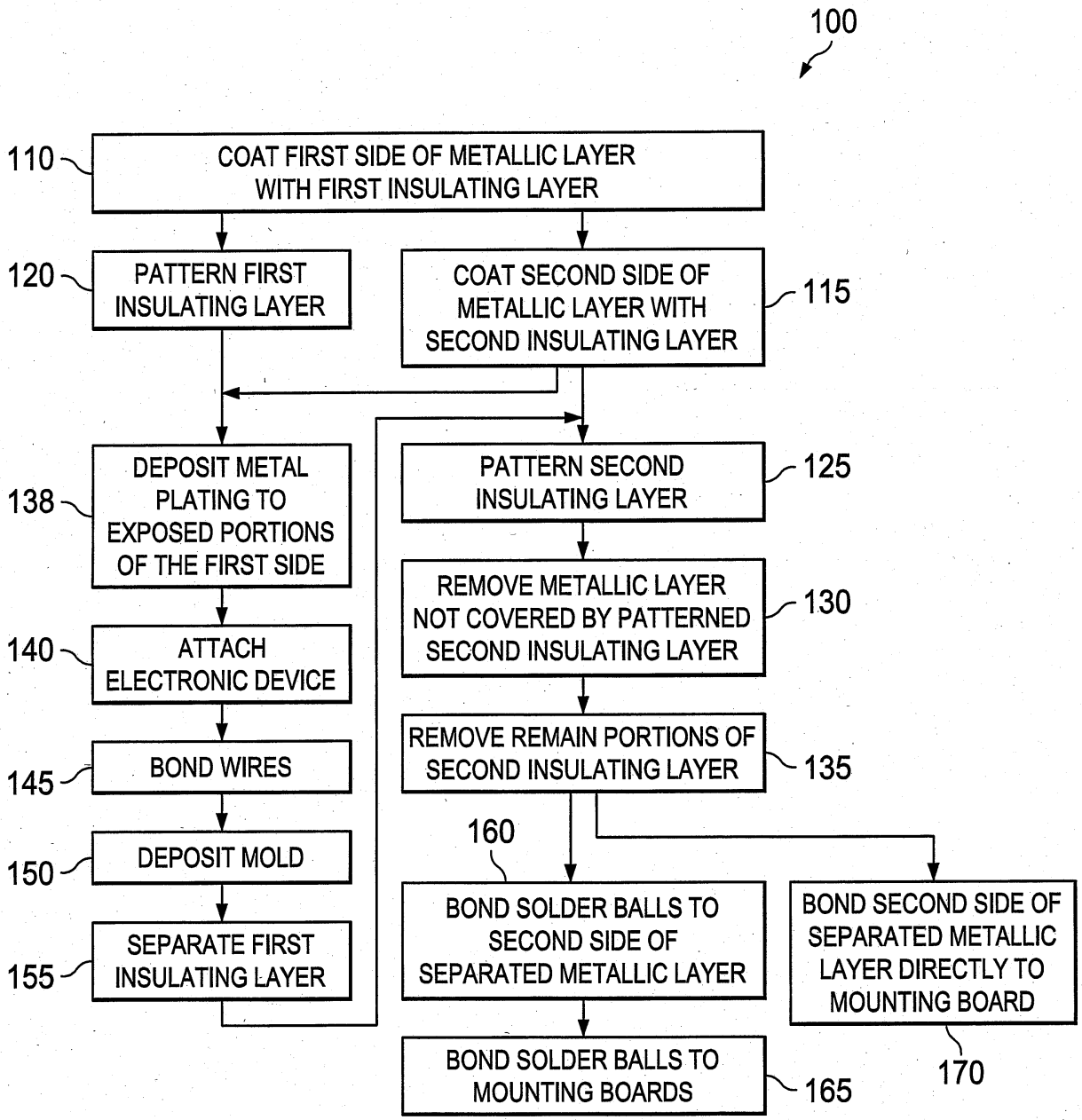

100
110
COAT FIRST SIDE OF METALLIC LAYER WITH FIRST INSULATING LAYER
120
PATTERN FIRST INSULATING LAYER
COAT SECOND SIDE OF METALLIC LAYER WITH SECOND INSULATING LAYER
115
138
DEPOSIT METAL PLATING TO EXPOSED PORTIONS OF THE FIRST SIDE
PATTERN SECOND INSULATING LAYER
125
140
ATTACH ELECTRONIC DEVICE
REMOVE METALLIC LAYER NOT COVERED BY PATTERNED SECOND INSULATING LAYER
130
145
BOND WIRES
REMOVE REMAIN PORTIONS OF SECOND INSULATING LAYER
135
150
DEPOSIT MOLD
160
155
SEPARATE FIRST INSULATING LAYER
BOND SOLDER BALLS TO SECOND SIDE OF SEPARATED METALLIC LAYER
BOND SECOND SIDE OF SEPARATED METALLIC LAYER DIRECTLY TO MOUNTING BOARD
170
BOND SOLDER BALLS TO MOUNTING BOARDS
165

FIG. 1

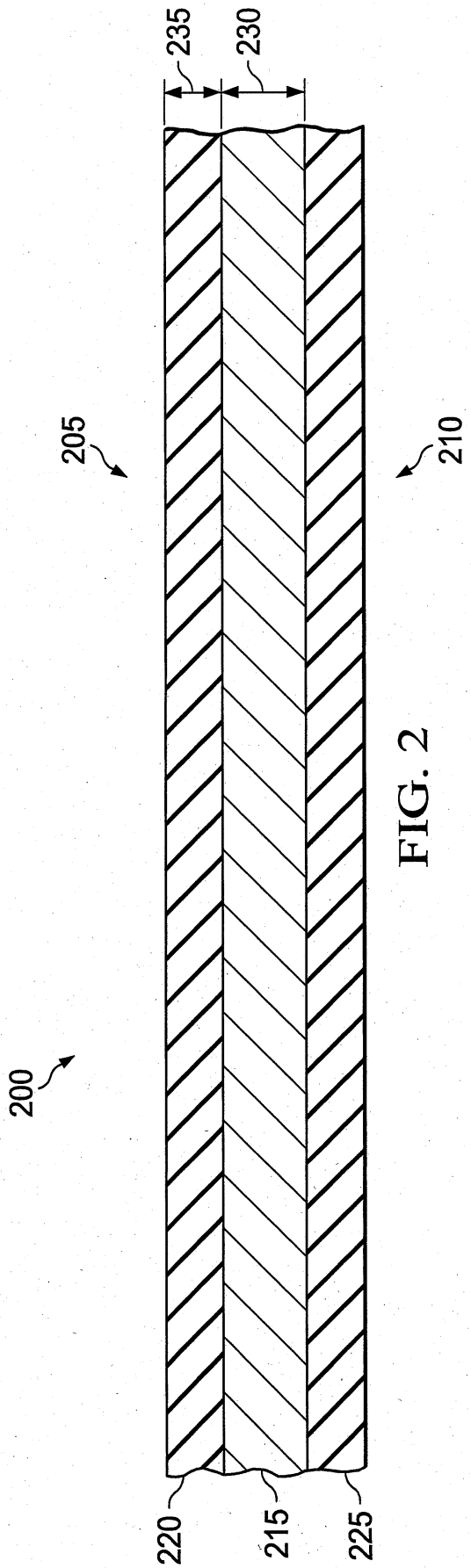

200
205
210
235
230
220
215
225

FIG. 2

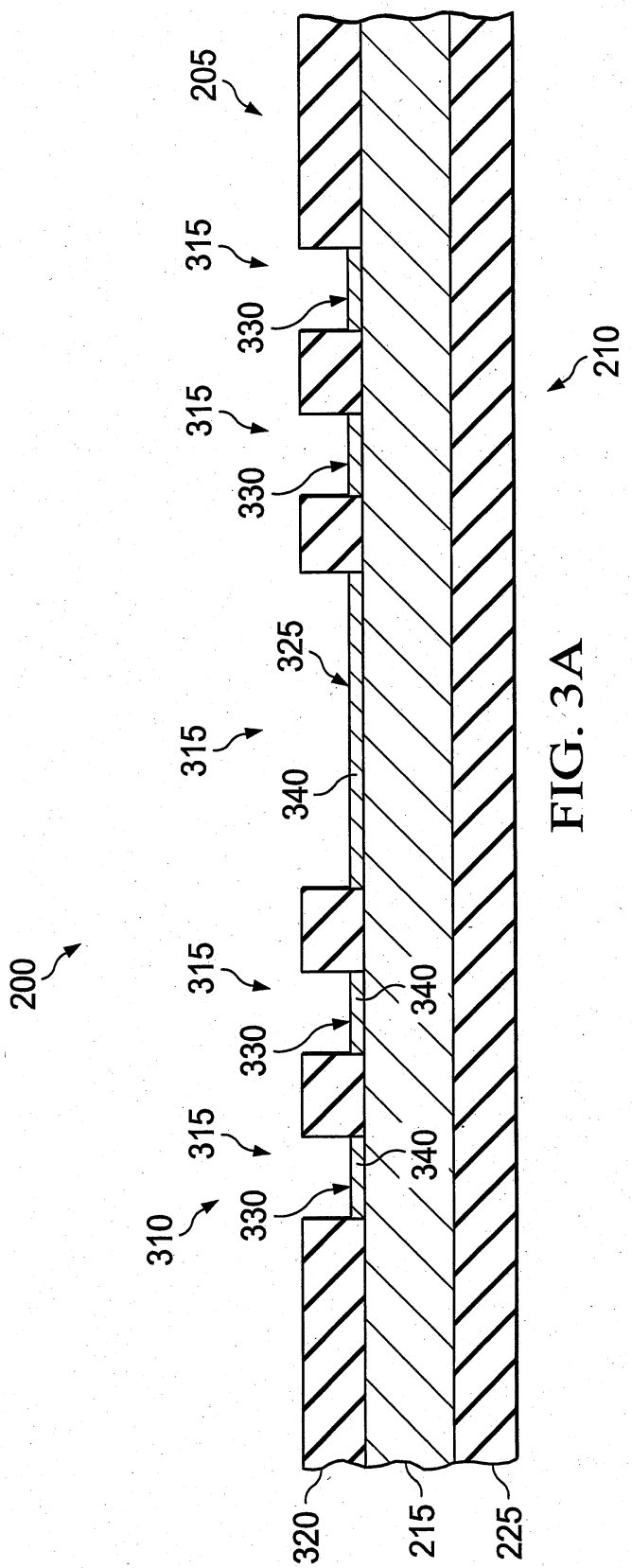

200
205
210
315
330
325
340
310
320
215
225

FIG. 3A

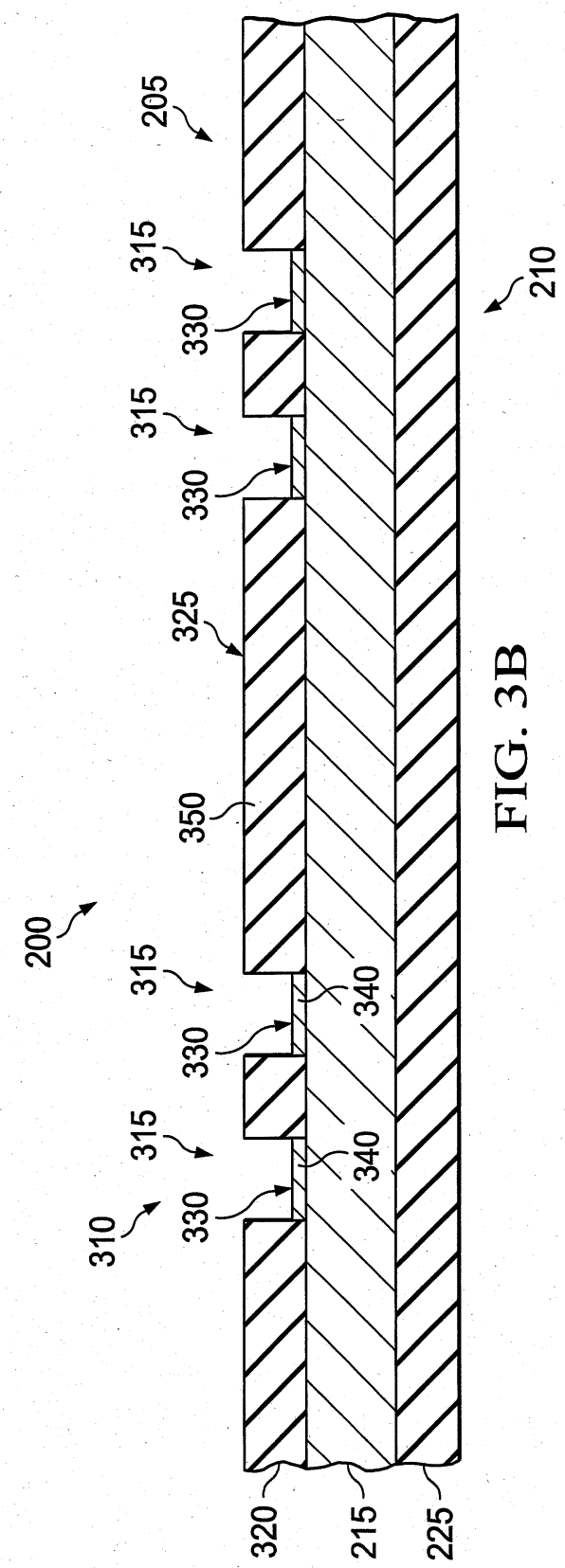

200
205
210
310
315
315
315
330
330
330
325
350
340
340
320
215
225

FIG. 3B

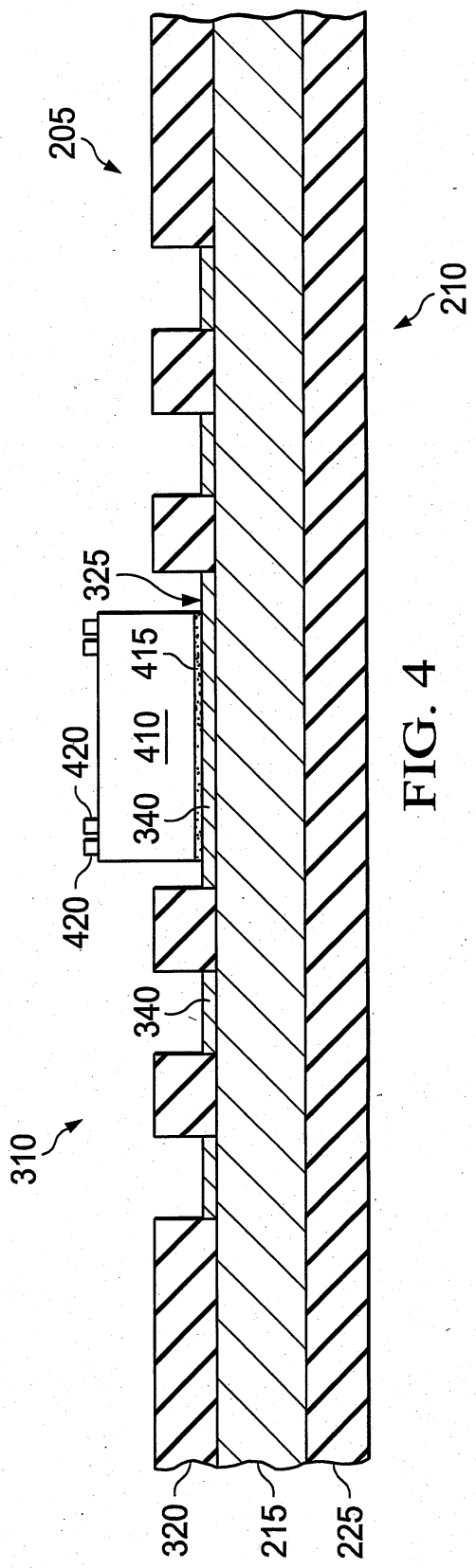

200
205
210
310
325
415
420
410
420
340
340
320
215
225

FIG. 4

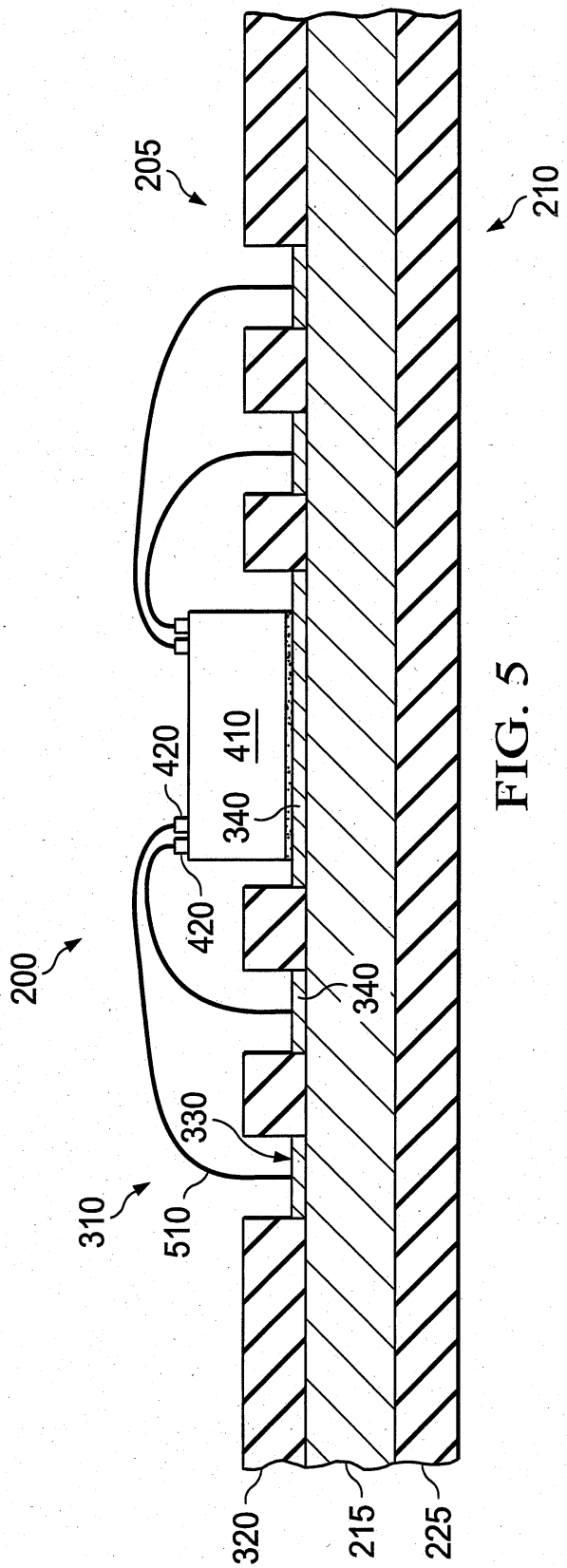

200
205
210
310
330
510
420
420
410
340
340
320
215
225

FIG. 5

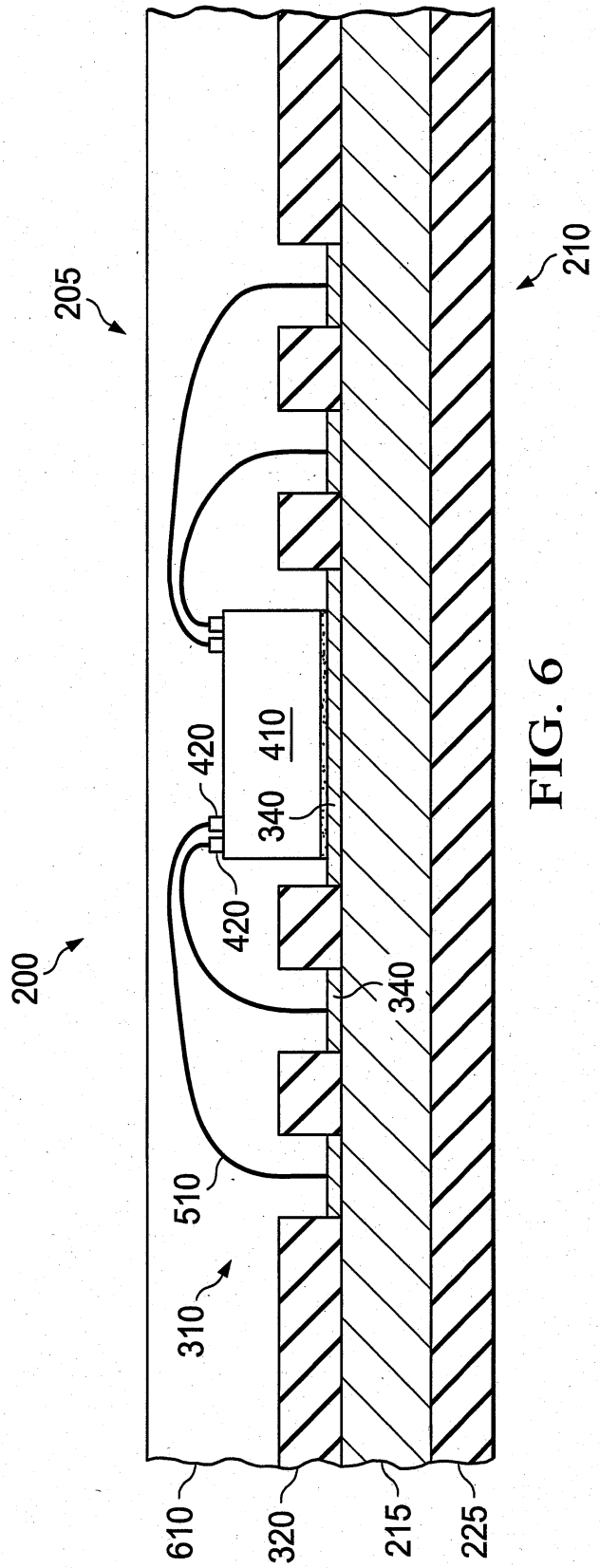

200
205
210
310
510
420
420
410
340
340
610
320
215
225

FIG. 6

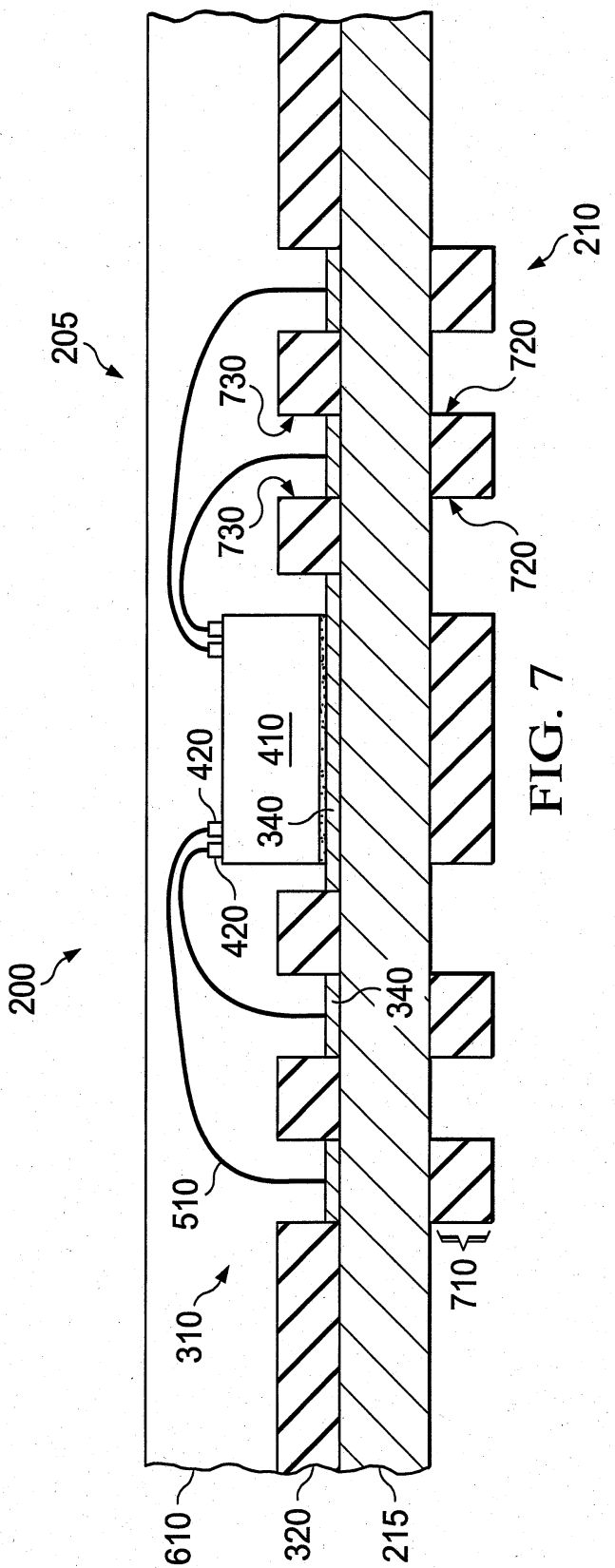

200
205
210
215
310
320
340
340
410
420
420
510
610
710
720
720
730
730

FIG. 7

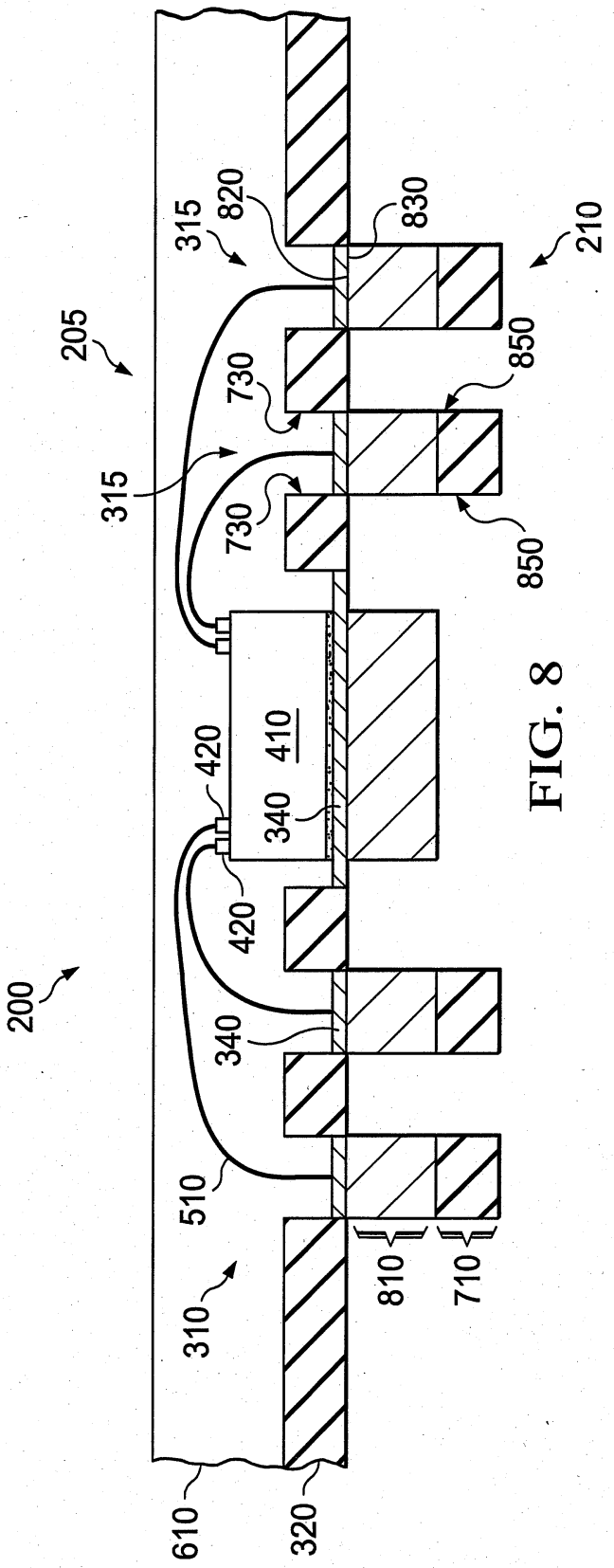

200
205
210
315
315
820
830
850
850
730
730
410
420
420
340
340
510
310
810
710
610
320

FIG. 8

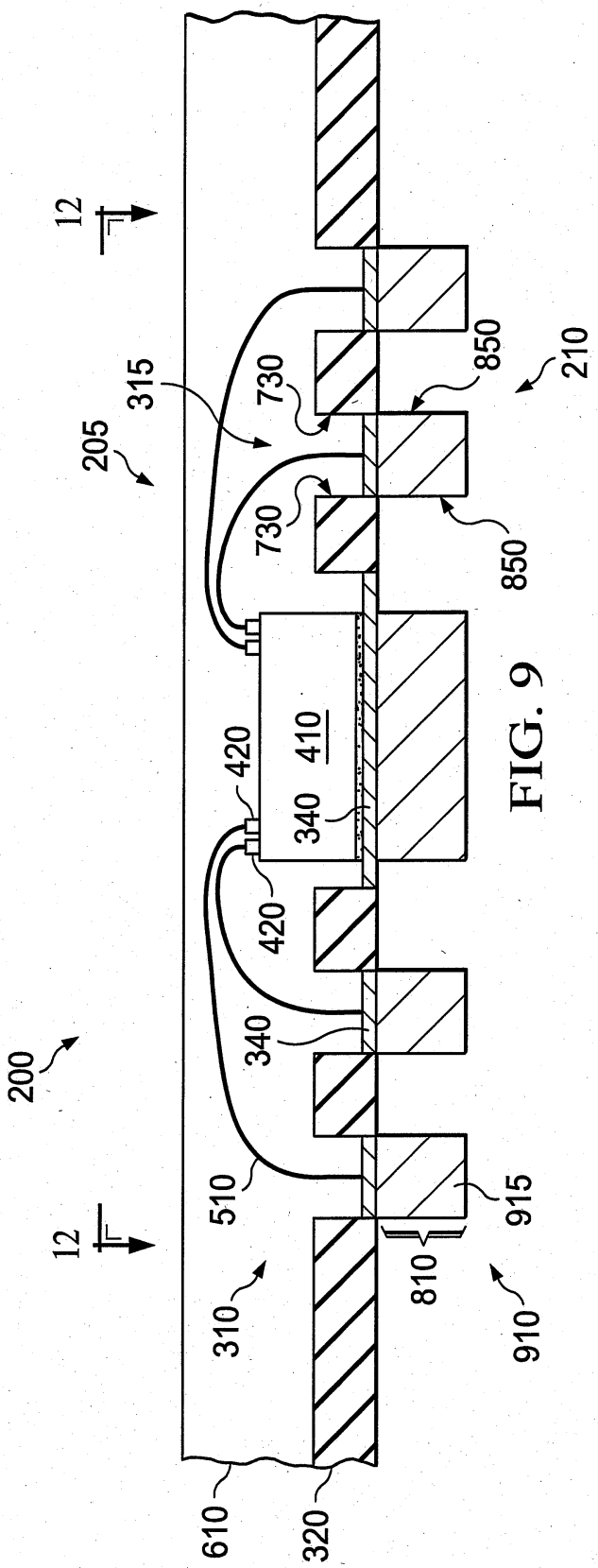

12
315
730
850
210
205
730
850
410
420
340
420
340
200
510
915
12
310
810
910
610
320

FIG. 9

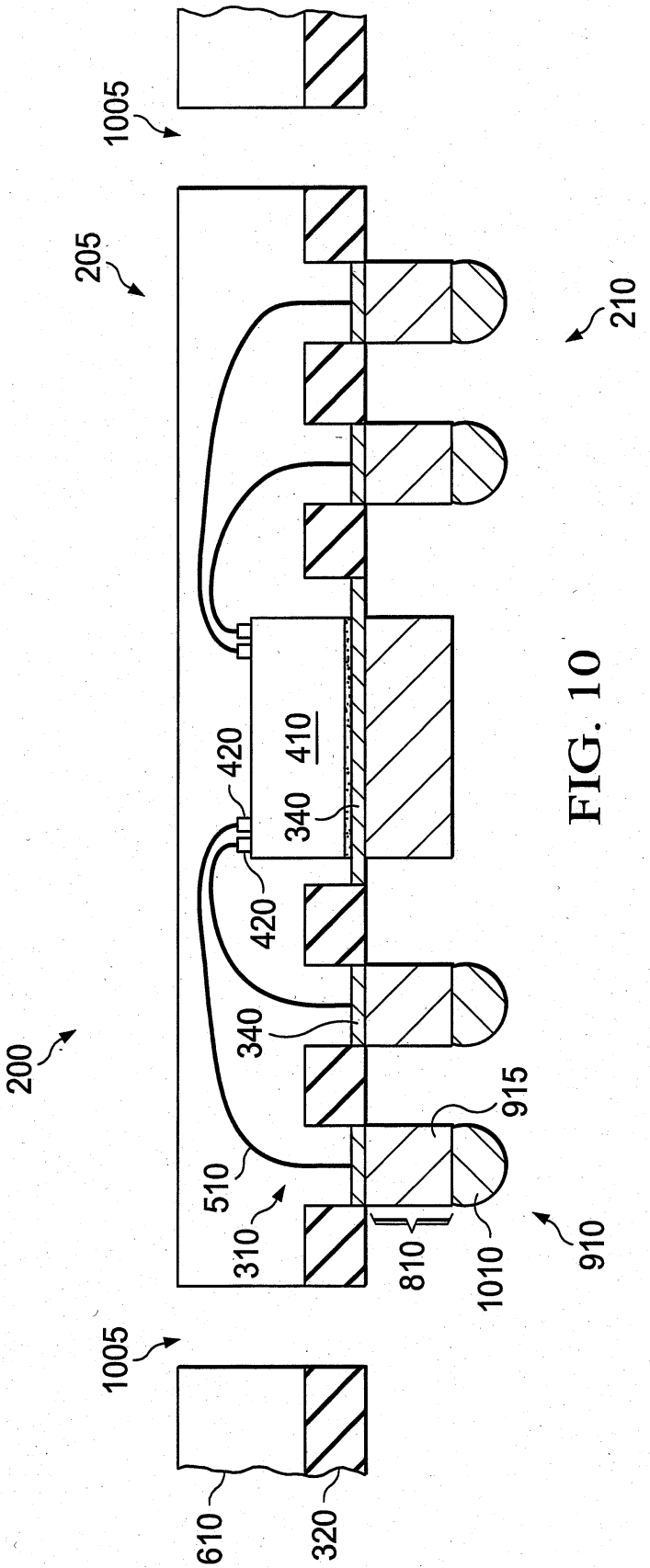

1005
205
210
420
410
340
420
340
200
915
510
310
810
1010
910
1005
610
320

FIG. 10

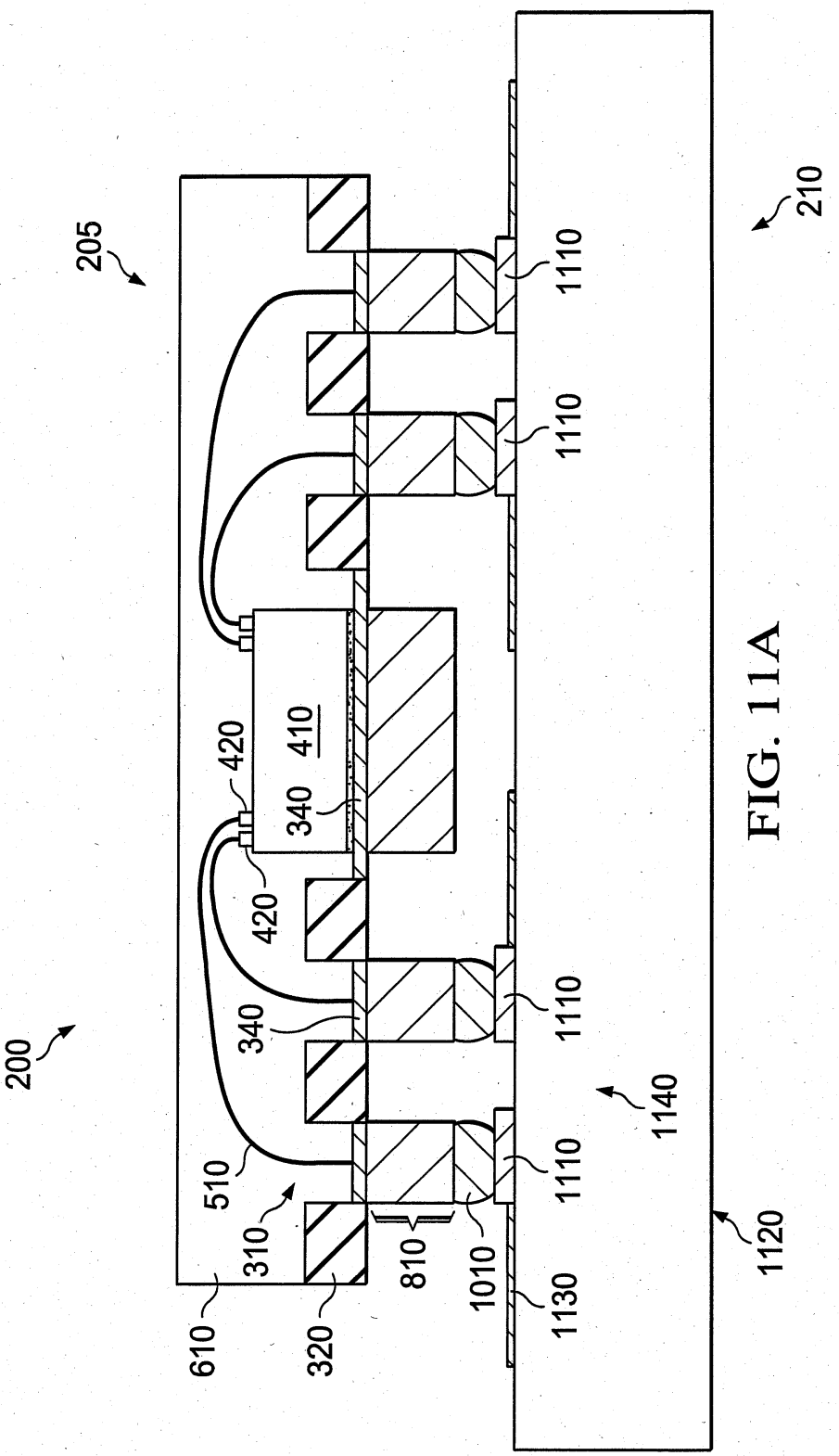

200
205
210
410
420
420
340
340
510
310
610
320
810
1010
1130
1120
1140
1110
1110
1110
1110
1110

FIG. 11A

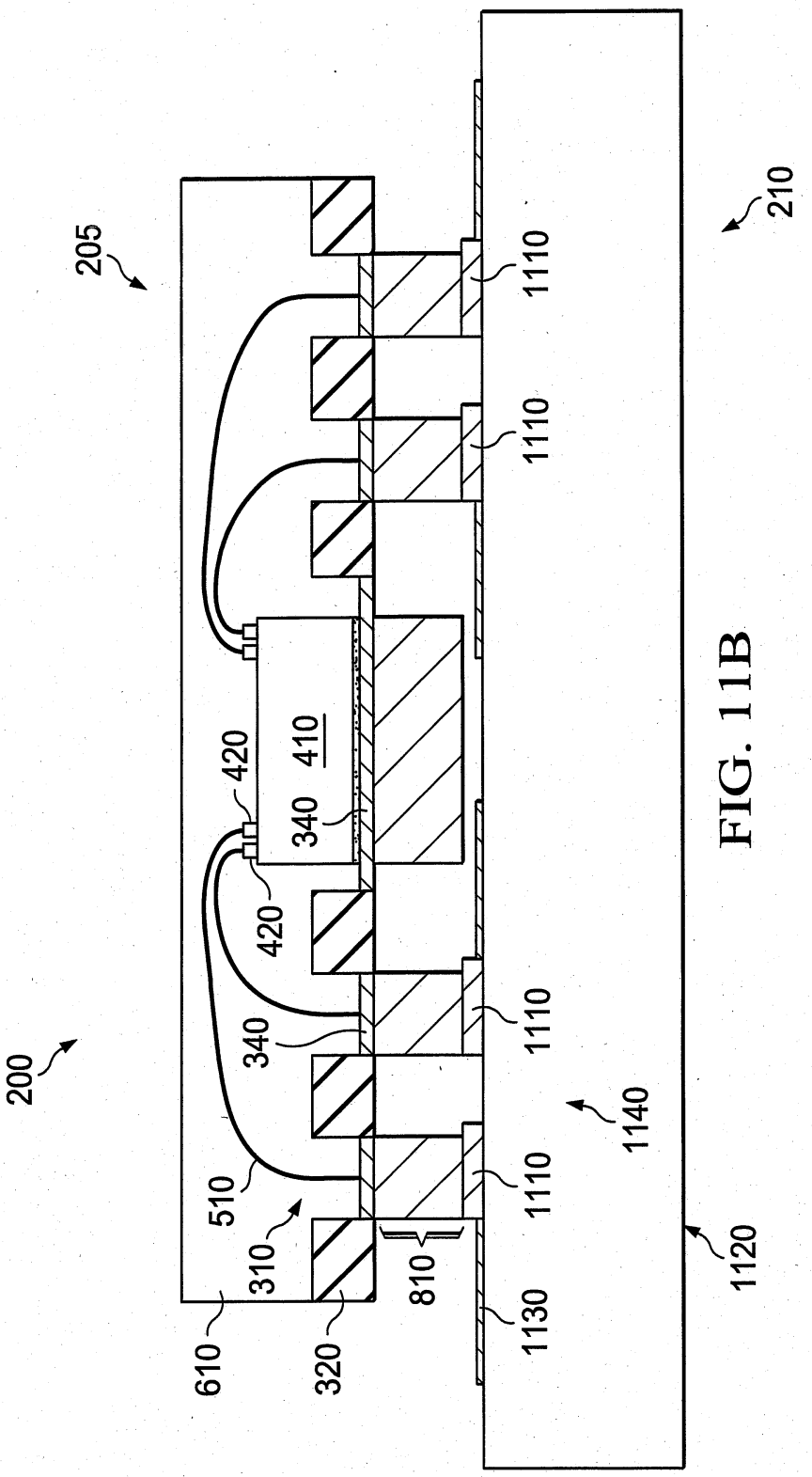

200
205
210
1110
1110
420
410
340
420
340
1110
1140
510
1110
310
810
1130
1120
610
320

FIG. 11B

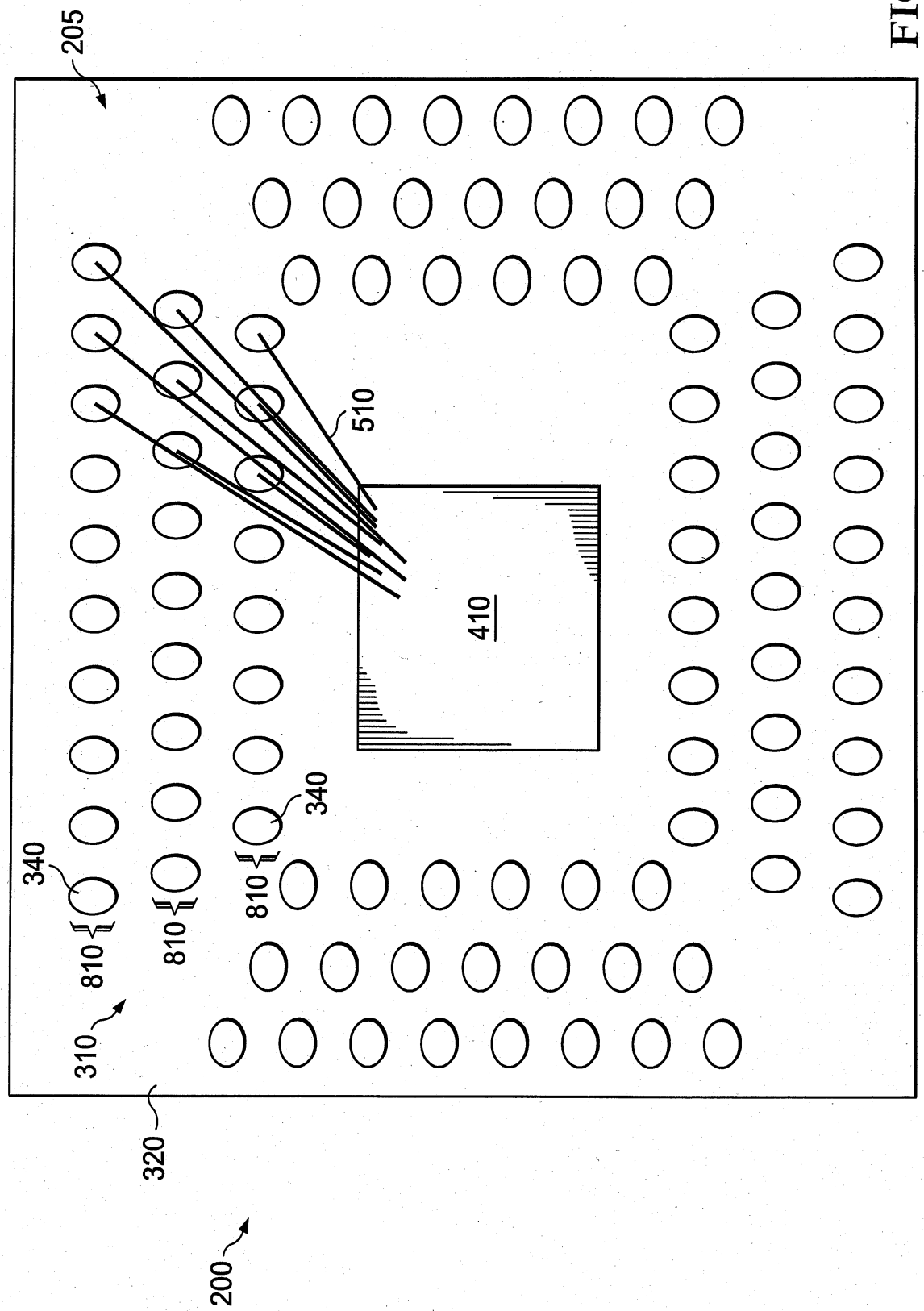


FIG. 12